

WHAT IS CLAIMED IS:

1. A flexible wiring film comprising a lead of an electric conductor, and an insulating film, wherein said lead has a hole in a portion exposed from said
5 insulating film.

2. The flexible wiring film according to Claim 1, wherein said hole is formed in a portion wider than a tip of said lead.
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3. The flexible wiring film according to Claim 1 or 2, wherein said hole is of a shape selected from a circle, an elongated circle, an oval, and an elongated oval.
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4. An apparatus comprising a lead of a flexible wiring film, a device chip electrically connected to the lead, and a sealant for sealing a connection portion between said lead and said device chip, wherein
20 said lead has a hole formed in a portion in contact with said sealant.

5. A semiconductor apparatus comprising a lead of a flexible wiring film, a semiconductor device chip
25 electrically connected to the lead, and a protecting member for protecting a surface of the semiconductor device chip, which are sealed with a sealant in a

peripheral portion of said semiconductor device chip,
wherein said lead has a hole formed in a portion in
contact with the sealant.

5 6. The semiconductor apparatus according to Claim
5, wherein at least a part of said hole is formed in a
region where a portion of the lead is sandwiched
between said semiconductor device chip and said
protecting member.

10 7. The apparatus according to Claim 4, wherein
said hole is formed in a portion wider than a tip of
said lead.

15 8. The semiconductor apparatus according to Claim
5, wherein at least one of a layer for preventing
reflection of external light and a layer for preventing
multiple reflection is formed between said lead and
said protecting member.

20 9. An image pickup system comprising:
a solid-state image pickup apparatus consisting of
the semiconductor apparatus as set forth in either one
of Claims 5 to 8;

25 an optical system for focusing light on said
solid-state image pickup apparatus; and

a signal processing circuit for processing an

output signal from said solid-state image pickup apparatus.

5 10. A flexible wiring film comprising a lead of
an electric conductor, and an insulating film, wherein
said lead has a hole adapted to be adhered to an
object.

10 11. A flexible wiring film comprising a lead of
an electric conductor, and an insulating film, wherein
said lead has a hole for enhancing to adhere.